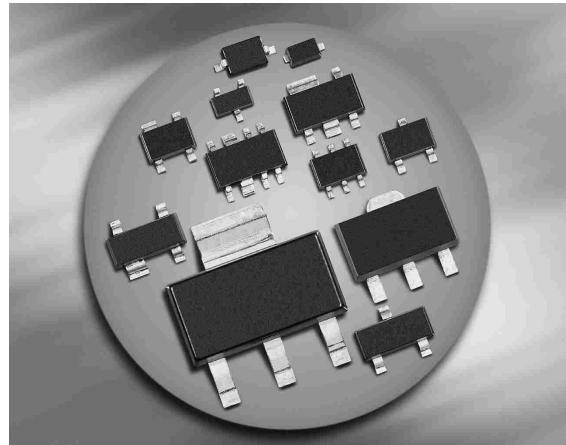
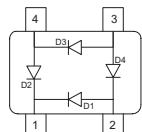


Silicon Switching Diode Array

- Bridge configuration
- High-speed switching diode chip



BGX50A



Type	Package	Configuration	Marking
BGX50A	SOT143	bridge	U1s

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	50	V
Peak reverse voltage	V_{RM}	70	
Forward current	I_F	140	mA
Total power dissipation $T_S \leq 74^\circ\text{C}$	P_{tot}	210	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

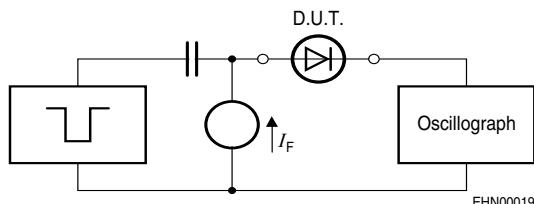
Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BGX50A	R_{thJS}	360	K/W

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current $V_R = 50 \text{ V}$	I_R	-	-	0.2	μA
$V_R = 50 \text{ V}, T_A = 150^\circ\text{C}$		-	-	100	
Forward voltage $I_F = 100 \text{ mA}$	V_F	-	-	1.3	V
AC Characteristics					
Diode capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_T	-	-	1.5	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}$, measured at $I_R = 1 \text{ mA}$, $R_L = 100 \Omega$	t_{rr}	-	-	6	ns

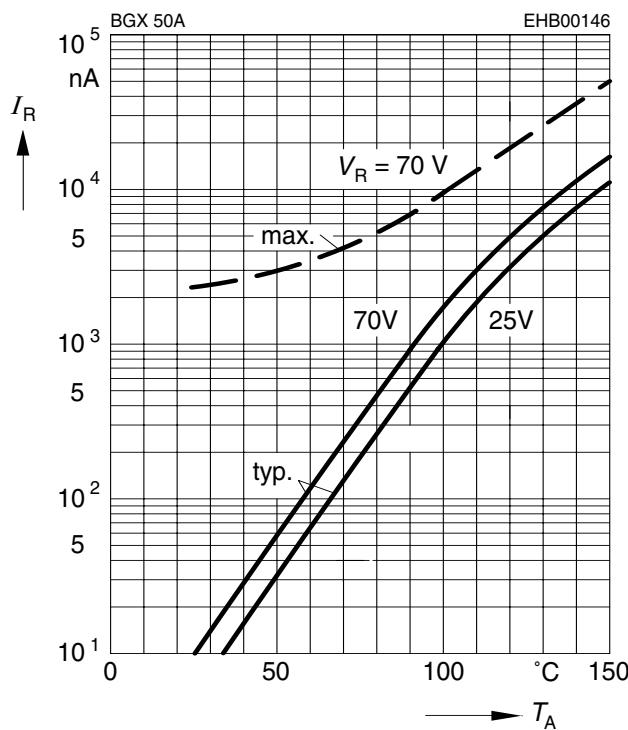
Test circuit for reverse recovery time


Pulse generator: $t_p = 100\text{ns}$, $D = 0.05$, $t_r = 0.6\text{ns}$,
 $R_i = 50\Omega$

Oscilloscope: $R = 50\Omega$, $t_r = 0.35\text{ns}$, $C \leq 1\text{pF}$

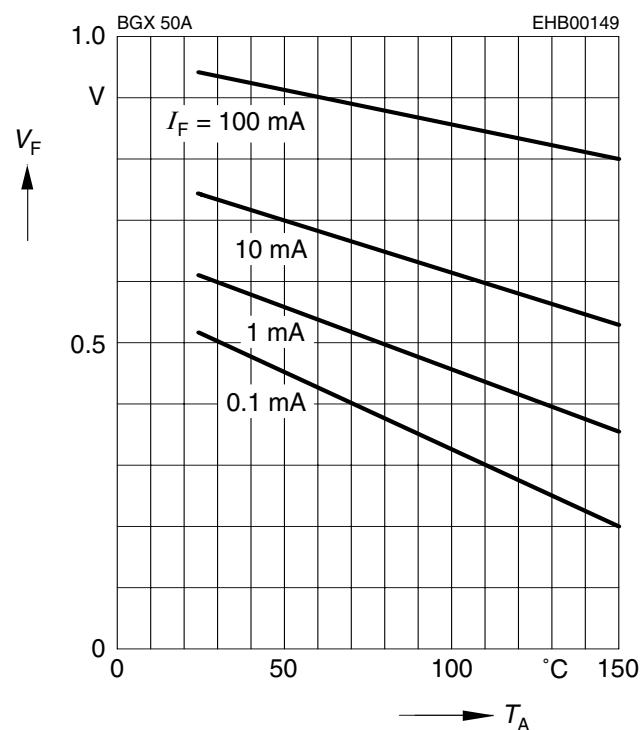
Reverse current $I_R = f(T_A)$

V_R = Parameter



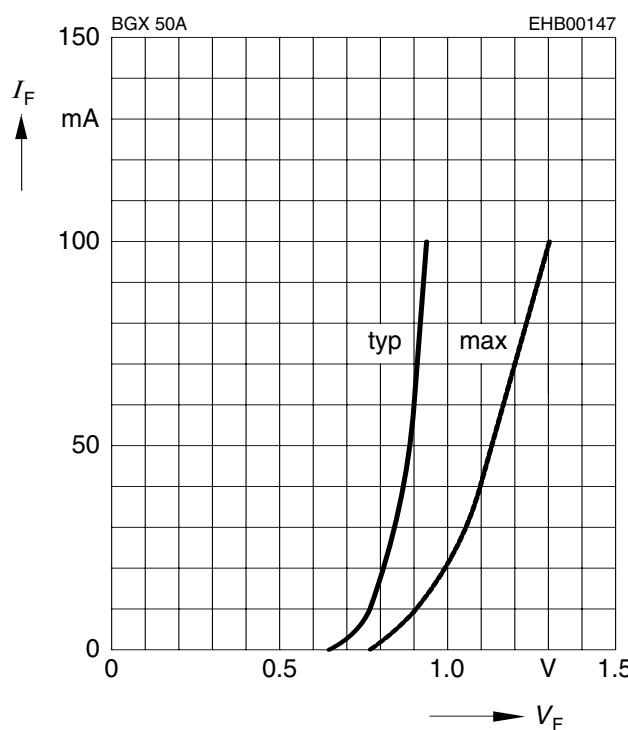
Forward Voltage $V_F = f(T_A)$

I_F = Parameter



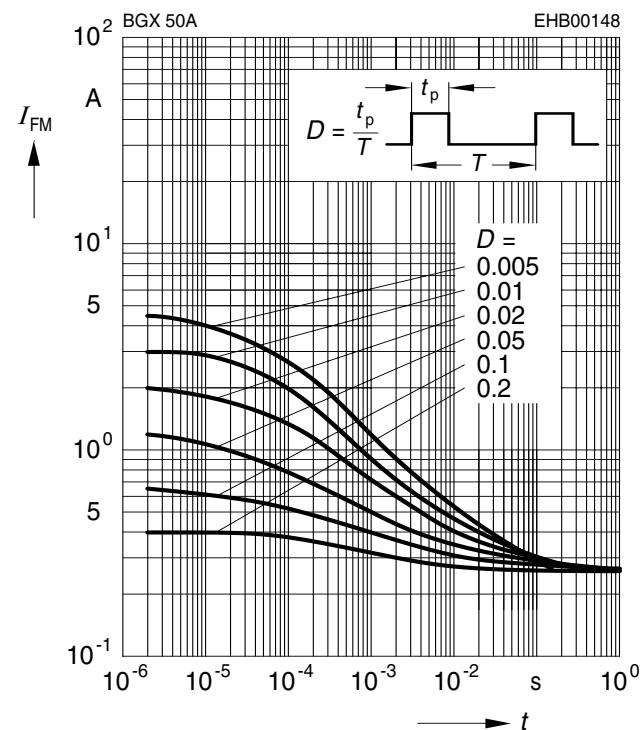
Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



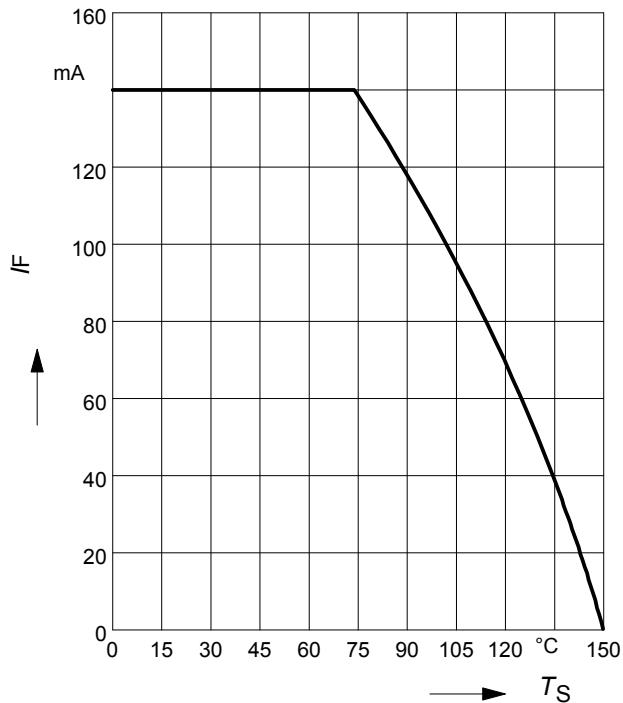
Peak forward current $I_{FM} = f(t_p)$

$T_A = 25^\circ\text{C}$

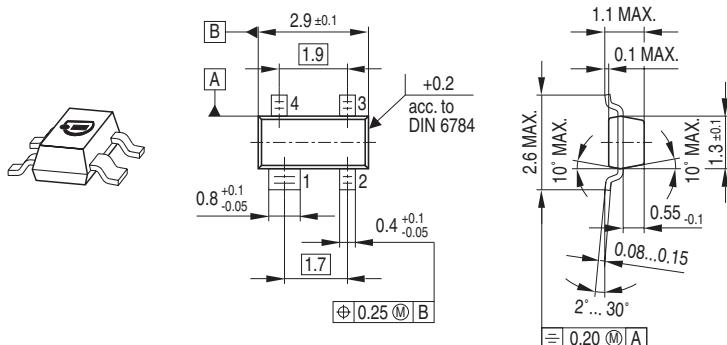


Forward current $I_F = f(T_S)$

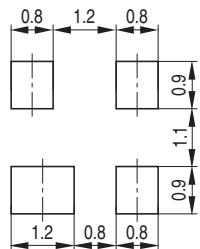
BGX50A



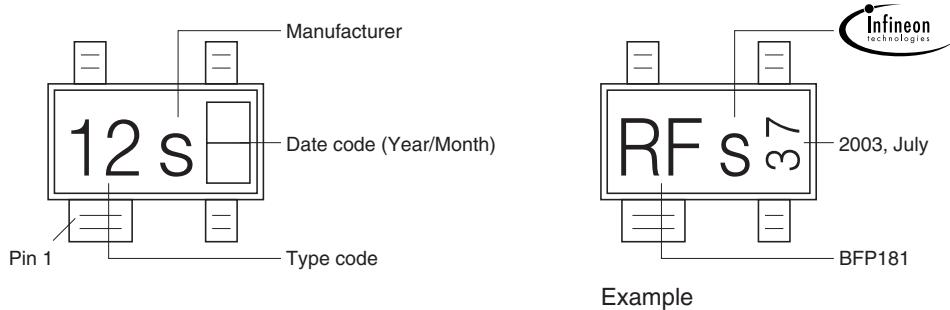
Package Outline



Foot Print

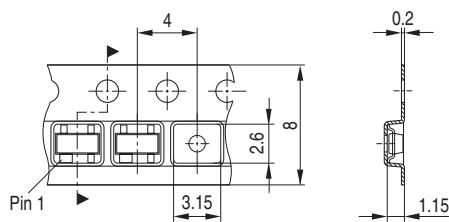


Marking Layout



Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
 Code E6433: Reel ø330 mm = 10.000 Pieces/Reel



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